

Single P-Channel MOSFET

DESCRIPTION

SMC2869ESD used trench technology are well suited for high efficiency fast switching applications, this MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, this devices are well suited for applications in the small surface mount package.

PART NUMBER INFORMATION

SMC 2869 E SD - TR G
 a b c d e f

a : Company name
 b : Product Serial number
 c : ESD Protection
 d : Package code SD: SOT-323
 e : Handling code TR: Tape&Reel
 f : Green produce code G: RoHS Compliant

FEATURES

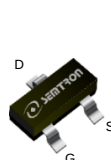
$V_{DS}=-20V$, $I_D=0.56A$

$R_{DS(ON)}=560m\Omega(Typ.)@V_{GS}=-4.5V$
 $R_{DS(ON)}=740m\Omega(Typ.)@V_{GS}=-2.5V$
 $R_{DS(ON)}=1000m\Omega(Typ.)@V_{GS}=-1.8V$
 $R_{DS(ON)}=1400m\Omega(Typ.)@V_{GS}=-1.5V$

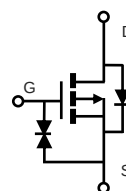
- ◆ High-speed switching, Low On-resistance
- ◆ 1.5V Low gate drive
- ◆ ESD protected

APPLICATIONS

- ◆ Load switch application for portable
- ◆ DC/DC converter



SOT-323



ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}C$ Unless otherwise noted)

Symbol	Parameter		Rating	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±10	V
I _D	Continuous Drain Current	T _A =25°C	-0.56	A
		T _A =70°C	-0.45	A
I _{DM}	Pulsed Drain Current ^B		-1.8	A
P _D	Power Dissipation ^A	T _A =25°C	0.36	W
		T _A =70°C	0.23	W
T _J	Operation Junction Temperature		-55/150	°C
T _{STG}	Storage Temperature Range		-55/150	°C

THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^A	$t \leq 10s$	-	$^{\circ}C/W$
	Thermal Resistance Junction to Ambient ^{AC}	Steady-State	350	$^{\circ}C/W$

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ Unless otherwise noted)

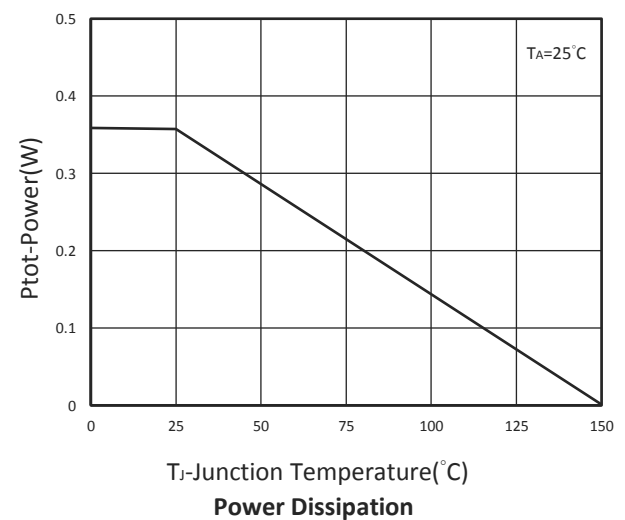
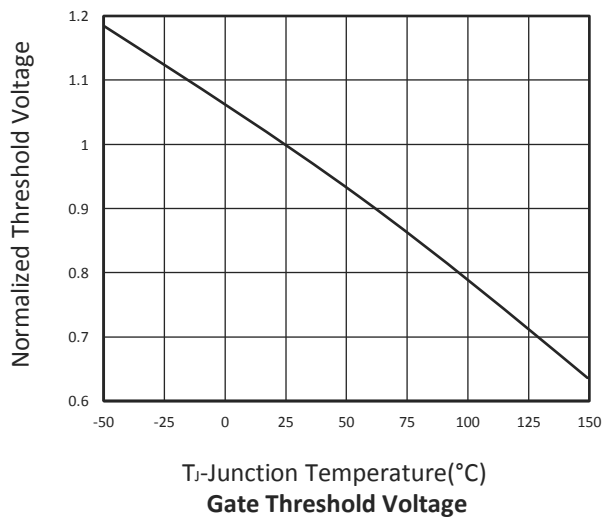
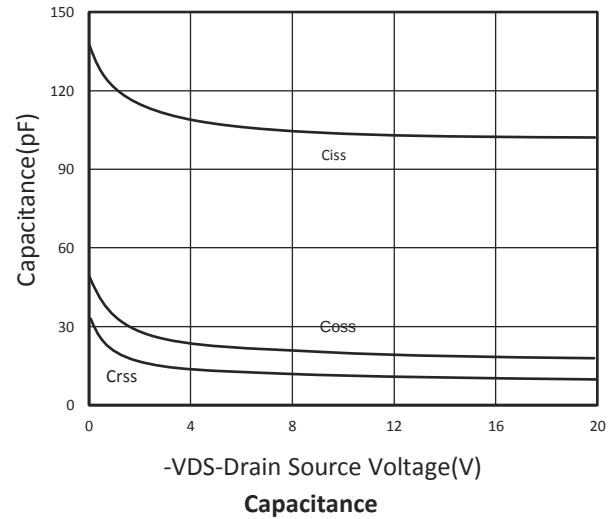
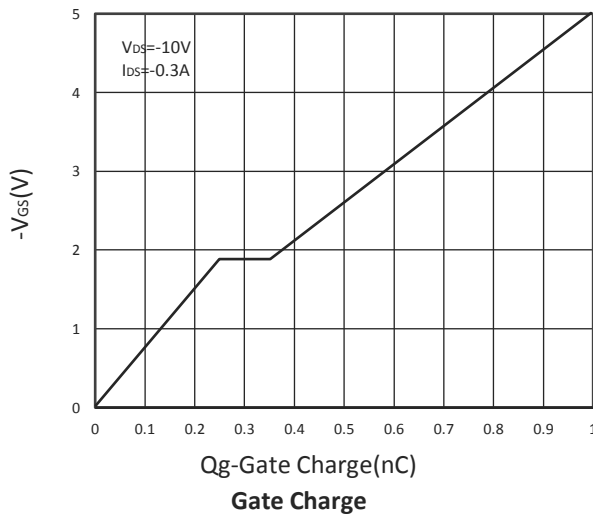
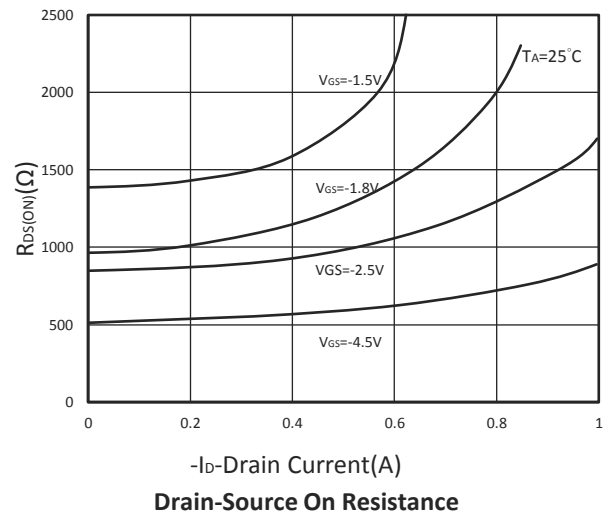
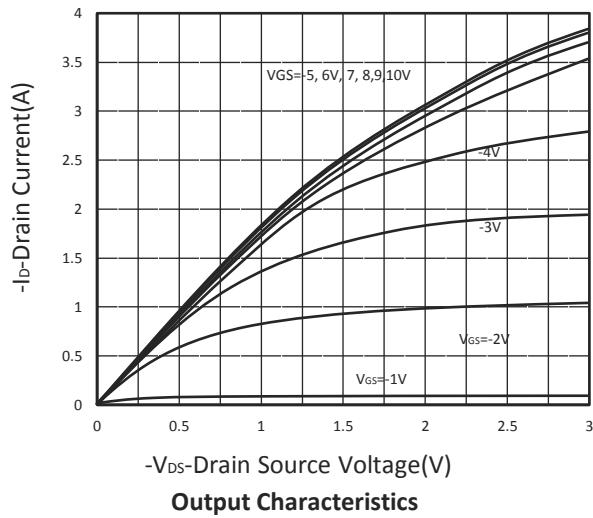
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
B _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.5	-0.7	-1	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±8V			±10	μA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V, T _J =25°C			1	μA
		V _{DS} =-12V, V _{GS} =0V, T _J =85°C			-10	
R _{DS(ON)}	Drain-source On-Resistance [Ⓟ]	V _{GS} =-4.5V, I _D =-0.56A V _{GS} =-2.5V, I _D =-0.3A V _{GS} =-1.8V, I _D =-0.2A V _{GS} =-1.5V, I _D =-0.1A		600 800 1000 1400	750 950 1300 1800	mΩ
Diode Characteristics						
V _{SD}	Diode Forward Voltage [Ⓟ]	I _S =-0.2A, V _{GS} =0V			-1	V
I _S	Diode Continuous Forward Current				-0.5	A
Dynamic and Switching Parameters ^F						
Q _g	Total Gate Charge	V _{DS} =-10V, V _{GS} =-4.5V I _D =-0.3A		1		nC
Q _{gs}	Gate-Source Charge			0.24		
Q _{gd}	Gate-Drain Charge			0.1		
C _{iss}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz		105		pF
C _{oss}	Output Capacitance			16		
C _{rss}	Reverse Transfer Capacitance			9.4		
t _{d(on)}	Turn-On Time	V _{DD} =-10V, V _{GS} =-4.5V R _G =4.5Ω, I _D =-0.3A		6.2		nS
t _r				19		
t _{d(off)}	Turn-Off Time			77		
t _f				231		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

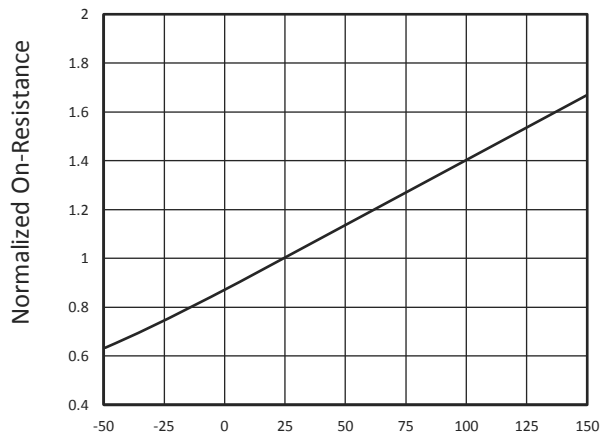
- A. Surface mounted on FR4 board using 1 in² pad size.
- B. Pulsed width limited by maximum junction temperature, $T_{J(MAX)}=150^\circ C$ (initial temperature $T_J=25^\circ C$).
- C. Using $\leq 10s$ junction-to-ambient thermal resistance is base on $T_{J(MAX)}=150^\circ C$.
- D. Pulse test width $\leq 300\mu s$ and duty cycle $\leq 2\%$.
- E. Guaranteed by design, not subject to production testing.

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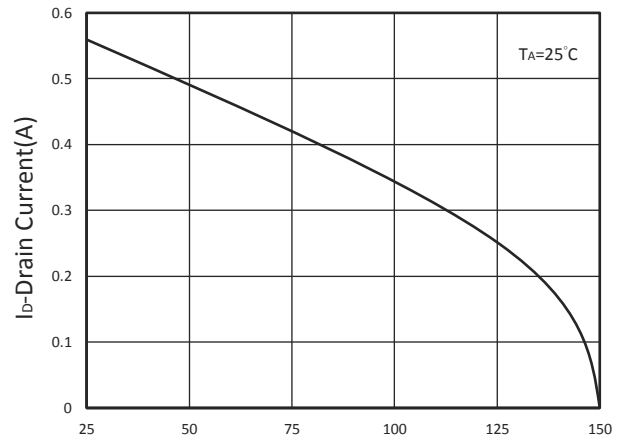
TYPICAL CHARACTERISTICS



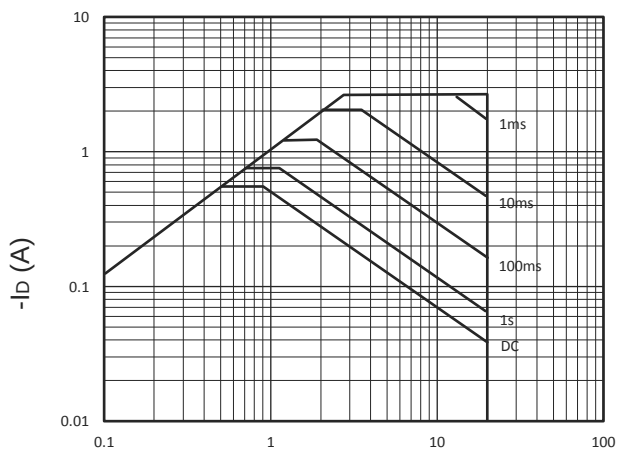
TYPICAL CHARACTERISTICS



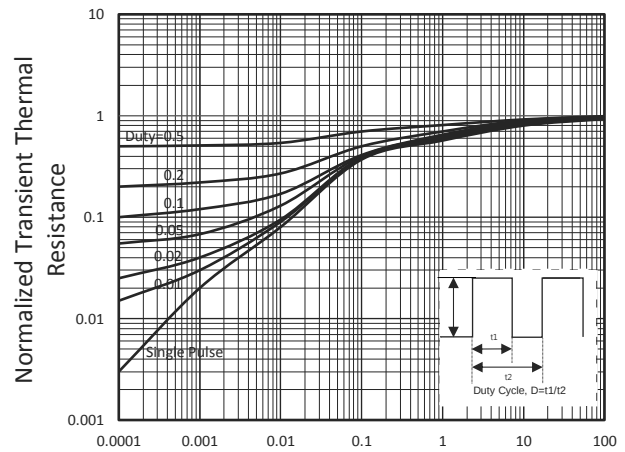
T_J -Junction Temperature($^{\circ}\text{C}$)
Drain-Source On Resistance



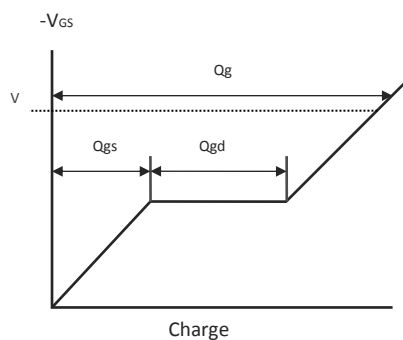
T_J -Junction Temperature($^{\circ}\text{C}$)
Drain Current vs T_J



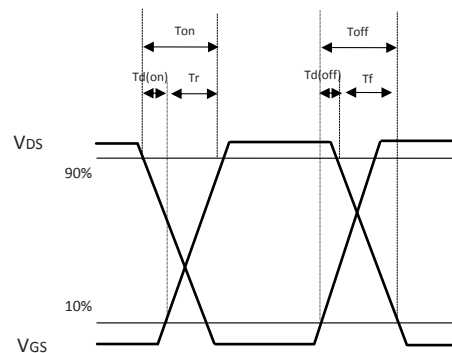
Maximum Safe Operation Area
 V_{DS} Voltage (V)



Square Wave Pulse Duration(Sec)
Thermal Transient Impedance

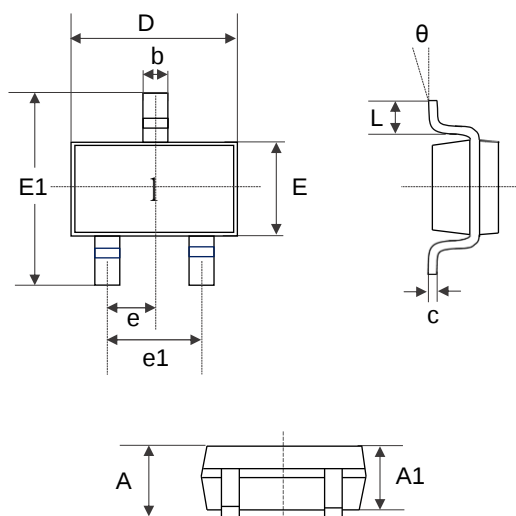


Gate Chrg Waveform

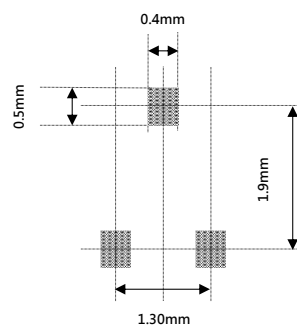


Switching Time Waveform

■ SOT-323 PACKAGE DIMENSIONS



Recommended Land Pattern



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.800	1.000	0.031	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.250	0.003	0.010
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.1500	2.450	0.085	0.096
e	0.650 BSC.		0.026 BSC.	
e1	1.200	1.400	0.047.	0.055
L	0.15	0.45	0.06	0.018
θ	0°	8°	0°	8°